

LINEAR SPLIT AXIS WIRE BONDER

ABSTRACT

A wire bonding machine for bonding a wire to a semiconductor device. The wire bonding machine includes a wire bonding head having a bonding tool mounted to it. The bonding tool is adapted to attach a wire end to a semiconductor device. A bonding head conveyance system translates the bonding tool in a vertical direction and translates the bonding tool along a first horizontal axis. A work table supports at least one semiconductor device to be wire bonded. A work table conveyance system translates the semiconductor device along a second horizontal axis.

Figure 1